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<p style="text-align: center;">Substitute for FORM PTO-1449 U.S. Department of Commerce Patent and Trademark Office <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b> (Use several sheets if necessary)</p> <p style="text-align: center;">Sheet 1 of 1</p>				Application Number	10/084,563
				Filing Date	2/26/2002
				First Named Inventor	Sergey Lopatin
				Attorney Docket No.	P1410
<b>U.S. PATENT DOCUMENTS</b>					
Examiner Initial	CiteN o.	U.S. Patent Document Number	Name of Patentee or Applicant of Cited Documents	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
<i>Lee</i>	1	6,197,181 B1	Chen, Lin Lin	3/6/2001	
<i>Lee</i>	2	6,022,808	Nogami, et al.	2/8/2000	
<b>FOREIGN PATENT DOCUMENTS</b>					
Examiner Initials'	Cite No.	Foreign Patent Document Office Number Code	Name of Patentee or Applicant of Cited document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appears
<b>OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS</b>					
Examiner Initials'	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article ( when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.			
<i>Lee</i>	1	PETER VAN ZANT, "Microchip Fabrication: A Practical Guide to Semiconductor Processing", 3 <sup>rd</sup> Ed., p. 392 and 397 (1997)			
<i>Lee</i>	2	A. Krishnamoorthy, D. Duquette and S. Murarka, "Electrochemical Codeposition and Electrical Characterization of a Copper-Zinc Alloy Metallization", in edited by Adricacos, et al., Electrochem Society Symposium Proceedings, Vol. 99-9, May 3-6, Seattle, p. 212			
<i>Lee</i>	3	J. Cunningham, "Using Electrochemistry to Improve Copper Interconnect", in Semiconductor International, Spring 2000 (May)			
<i>Lee</i>	4	L. Chen and T. Ritzdorf, "ECD Seed Layer for Inlaid Copper Metallization" in edited by Andricacos, et al., Electrochem Society Proceedings, Vol. 99-9, May 3-6, Seattle, p. 122			
Examiner Signature: <i>Lin Lin May Lee</i>			Date Considered: 4/3/03		

<sup>1</sup>Unique citation designation number. <sup>2</sup>See attached Kinds of U.S. Patent Documents. <sup>3</sup>Enter Office that issued the document, by the two-letter code (WIPO Standard ST 3). <sup>4</sup>For Japanese patent documents, the indication of the year of the reign of the Emperor must

<sup>1</sup>Unique citation designation number. <sup>2</sup>See attached Kinds of U.S. Patent Documents. <sup>3</sup>Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). <sup>4</sup>For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. <sup>5</sup>Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup>Applicant is to place a check mark here if English Language Translation is attached.